### Welcome to O-leading

O-Leading strives to be your one stop solution partner in EMS supply chain, including PCB design , PCB fabrication and PCB assembly ,We provide some of the most advanced PCB technology, including HDI PCBs,multilayer PCBs, Rigid-Flexible PCBs.We can support from quick turn prototype to medium & mass Production.(Professional Rigid Flexible PCB Supplier for Raspberry Pi 4 ABS Case)

In general, our global customers are very impressed with our services:Rapid response, competitive price and quality commitment.Providing more valuable technical service and overall solution is the way O-leading forward.

Looking to the future, O-leading will concentrate on the innovation and development of electronics manufacturing technology as always, and make persistent efforts on PCB & PCBA one-stop service to provide first-class services and create more value for our customers.

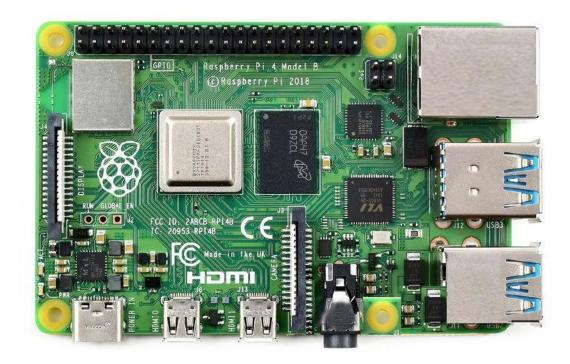
PLEASE CLICK THESE FOR MORE INFORMATION Low Cost PCB Fabrication POE Oem Manufacturing



Product Description

# Raspberry Pi 4 **BGB RAM**

More Powerful Processor, Richer Multi-Media Capability, Faster Networking







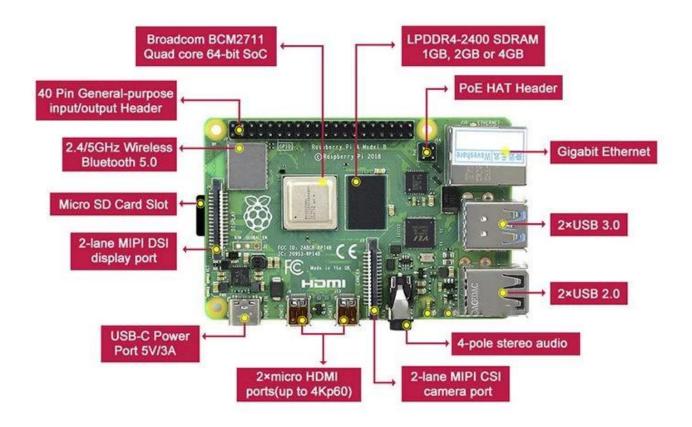


#### **IMPROVEMENTS OF V1.2**

- 1. In additional to the official USB Type-C cable, Pi 4B V1.2 now supports more other USB Type-C cables
- 2. Relocates the WLCSP SD card voltage switch, to protect the Pi 4B better
- 3. Optimizes silkscreen printing, to minimize the soldering and bridging in manufacturing process

# Raspberry Pi 4 Completely Upgraded

More Powerful Processor, Richer Multi-Media Capability, Faster Networking



BCM2711B0 64-bit 1.5GHz Quad-core Processor	Choice Of RAM 2GB/4GB/8GB	4K Dual HDMI  4K High Resolution Dual Displays
Faster Networking  Gigabit ETH, Bluetooth 5.0, Dual-band WiFi	New USB3.0	USB-C Power Upgraded Power Supply, More Powerful

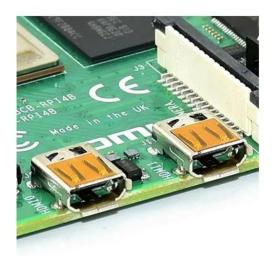
# BCM2711B0

64-Bit Quad-Core Processor

Cortex-A72 ARM Architecture

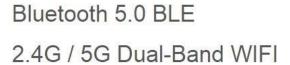
64-bit Quad-core 1.5GHz Frequency

Faster, more powerful CPU
Provides smooth experience like X86 desktop PC

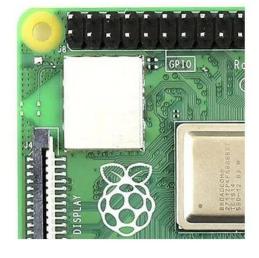


# 4K Ultra High Definition Dual Micro HDMI

Upgrade to dual micro HDMI instead of a full size HDMI Dual displays, up to 60fps refreshing rate



Upgraded Bluetooth 5.0 BLE, better performance Dual-band WIFI, along with the Gigabit Ethernet Better connectivity, faster and more stable networking





# New USB3.0 Ports Faster Data Transmission

2xUSB 3.0 + 2xUSB 2.0

No more trouble when connecting with high speed devices

# Raspberry Pi Versions Comparing

	ZERO	ZEROW/ WH	3A+	3B	3B+	4B	
soc	E	3CM2835		BCM2837B0		BCM2711B0	
CPU		ARM11 -core 700MHz	ARM Cortex-A53 Quad-core (3B 1.2GHz, 3A+/3B+ 1.4GHz)			ARM Cortex-A72 Quad-core 1.5GHz	
GPU		Broa	adcom VideoCore	V@400MHz		Broadcom VideoCore IV@500MHz	
RAM		512MB	512MB	1GB		Choice of 2GB/4GB/8GB	
USB	1x	micro USB	1x USB2.0	32.0 4x USB2.0		2x USB2.0 + 2x USB3.0	
HDMI	M	icro HDMI		HDMI		Mini HDMI	
Bluetooth	N/A	Bluetooth 4.1	Bluetooth 4.2	Bluetooth 4.1	Bluetooth 4.2	Bluetooth 5.0	
WiFi	N/A	802.11 b/g/n	3В	: 802.11 b/g/n, ot	hers: 802.11 b/g/n/a	c 2.4GHz/5GHz dual band	
Ethernet		N/A	1001	0Mbps (USB)		1000Mbps	
PoE			N/A			Yes	
Power Input			Micro USB (5\	/ 2.5A)		USB Type-C (5V 3A)	
Dimensions	65	× 30 x 5 mm	65 × 56 mm		85 x 5	6 x 17 mm	

# **2GB/4GB/8GB WHICH SHOULD I CHOOSE?**

2GB Suitable for running lots apps while GUI is not required, e.g. robot controller and smart car.

Suitable for graphic task or Internet application, e.g. watching video as normal PC, or deploying a network server.

Suitable for complicate multi-tasking, heavy server workloads e.g. dual display 4K video playing, AI depth vision learning.

The total operational performance of Pi 4B is more than triple the 3B+'s, even the 2GB variant. Larger RAM has minor impact on performance if the RAM is just enough, therefore, we should choose the RAM capacity that best fits the target project. It is unnecessary to always choose the largest RAM.

# **Applications**

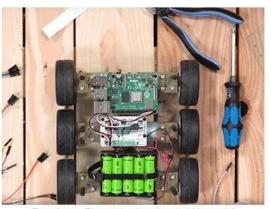
Your Tiny, Dual-Display, Desktop Computer ...And Robot Brains, Smart Home Hub, Media Center, Game Console...



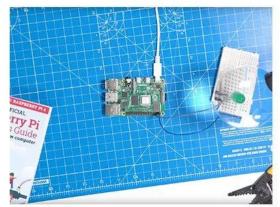
tiny dual-display desktop (balance work and life)



Raspberry Pi game console (relive retro games)



Raspberry Pi smart robot (try the Al magic)



Study and development (DIY endless possibilities)

# Our Team

#### To be #ELIABLE

Quality first ,

Customer supreme,

Scientifically management,

Striving for famous brand





# THE CUSTOMER IS KING





#### To be VALUABLE

Science and technology keeps head ,

Put people first,

Be precise and practical,

contribute sincerely

#### Factory PCB



Automatic vacuum press machine



Drilling Machine



Pattern Plating Machine



Scrubbing Machine



Developing Machine



Routing Machine



High-speed flying probe machine



E-test Machine

#### Factory SMT





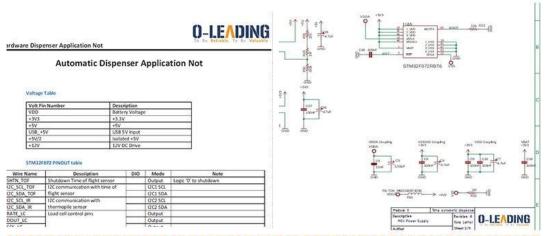








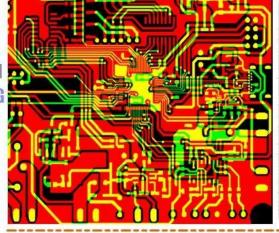
### **HOW O-LEADING MAKE A PROJECT FOR YOU**



### **HARDWARE** schematics

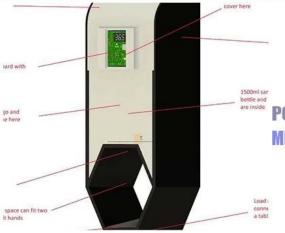
### **PCB PRODUCTION COMPONNETS SOURCING**





Qty	Value	Device	Parts	Description
4	AK500/2	AK500/2	X1, X2,	CONNECTOR
1	AK500/3	AK500/3	X7	CONNECTOR
1	1241148	MA04-2	SV2	8,000 F. 100,11 S. 10 (10,000
1	PPPC04	MA04-2	SV1	8 POS , 4*2 FEMALE PIN HEADE
1	ML10	ML10	SV4	HARTING
1	8MHZ	XTALL_CSTCE8M	X5	STCE8M00G52-R0 RESONATOR
1	OR	R-0603	R53	Thick Film Resistors - SMD 0603
2	10R	R-0603	R12, R5	Thick Film Resistors - SMD 0603
8	100R	R-0603	R1, R2,	Thick Film Resistors - SMD 0603
1	270R	R-0805	R15	Thick Film Resistors - SMD 0605
1	330R	R-0603	R11	Thick Film Resistors - SMD 0603
9	680R	R-0603	R20, R3	Thick Film Resistors - SMD 0603
17	1k	R-0603	R9, R10	Thick Film Resistors - SMD 0603
2	4.7k	R-0603	R17, R6	Thick Film Resistors - SMD 0603
2	5.1k	R-0603	R18, R1	Thick Film Resistors - SMD 0603
9	10k	R-0603	R16, R3	Thick Film Resistors - SMD 0603
^	001	0.0000	200 05	TI . I FI D





**PCB** Assembly **MECHANICAL DESIGN** 





































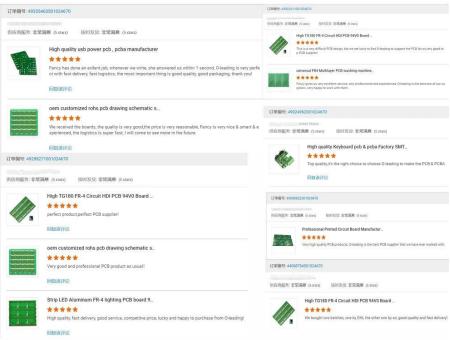


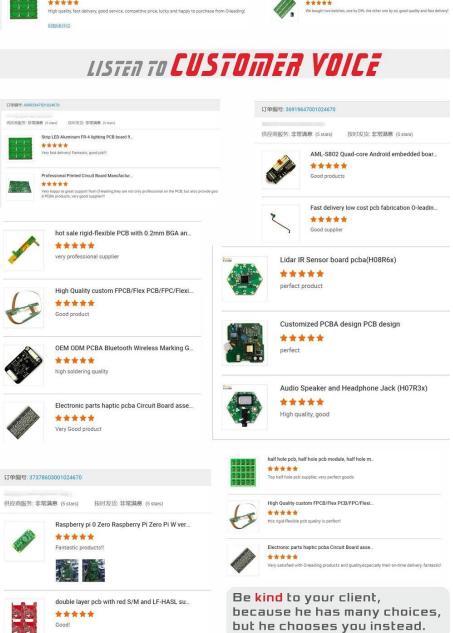




D-LEADING CUSTOMER REVIEW

#### customaa voica is **extraemely important** to us







# Certifications

#### O-LEADING *TRANING*



#### Кеер *L Е Д Я Л Л Б*

There's a phrase in Buddhism, 'Beginner's mind.'

lt's wonderful to have a beginner's mind

# WE HAVE A DREAM

#### Кеер *аппппБ*

I would like to live to study and not study to live.

----Bacon









Test Report

No. SZXEC1900530401

Date: 30 Mar 2019

O-LEADING SUPPLY CHAIN (HK) CO., LIMITED

1313.FLOOR 13. FORTUNE BUILDING, DANSHUI TOWN, HUIYANG DISTRICT, HUIZHOU, GUANGDONG,

The following sample(s) was/were submitted and identified on behalf of the clients as : OSP

SGS Job No. : Date of Sample Received: 22 Mar 2019

RP19-005089 - SZ

22 Mar 2019 - 30 Mar 2019

Testing Period : Test Requested :

Selected test(s) as requested by client.

Test Method :

Please refer to next page(s).

Test Results :

Please refer to next page(s).

Conclusion:

Based on the performed tests on submitted sample(s), the results of Lead, Mercury, Cadmium, Hexavalent chromium, Polybrominated biphenyl set (PBBs), Polybrominated diphenyl ethers (PBDEs) and Phthalates such as Bis(2-ethylnexyl) phthalate (DEHP), Butyl benzyl phthalate (BBP), Dibutyl phthalate (DBP), and Disobutyl phthalate (DBP) comply with the limits as set by RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

Signed for and on behalf of SGS-CSTC Standards Technical Services Co., Ltd. Shenzhen Branch

lina

Tina Fan Approved Signatory



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### SGS

No. SZXEC1900530401

Date: 30 Mar 2019

Page 2 of 6

Test Report Test Results :

Test Part Description :

SN1

SGS Sample ID SGS Sample ID Description SZX19-005304.001 Green"PCB"

(1) 1 mg/kg = 1 ppm = 0.0001% (2) MDL = Method Detection Limit

(3) ND = Not Detected ( < MDL )

(4) "-" = Not Regulated

#### RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU

Test Method : With reference to IEC 62321-4:2013+A1:2017, IEC62321-5:2013, IEC62321-7-2:2017, IEC 62321-6:2015 and IEC62321-8:2017, analyzed by ICP-OES, UV-Vis and GC-MS.

Test Item(s) Limit Unit Cadmium (Cd) 100 ND mg/kg Lead (Pb) 1,000 Mercury (Hg) Hexavalent Chromium (Cr(VI)) 1.000 Sum of PBBs ND 1.000 mg/kg Monobromobiphenyl ND ND ND Dibromobiphenyl Tribromobiphenyl mg/kg mg/kg mg/kg mg/kg ND ND ND Tetrabromobiphenyl Pentabromobiphenyl Hexabromobiphenyl mg/kg mg/kg mg/kg Heptabromobiphenyl ND ND ND ND Octabromobiphenyl Nonabromobiphenyl Decabromobiphenyl mg/kg mg/kg mg/kg ND ND ND Sum of PBDEs 1,000 Monobromodiphenyl ethe Dibromodiphen yl ether mg/kg Tribromodiphenyl ether mg/kg ND Tetrabromodiphenyl ether Pentabromodiphenyl ether



Max

Max

#### UL Product iQ™



### ZPMV2.E490354 - WIRING, PRINTED - COMPONENT

#### Wiring, Printed - Component

See General Information for Wiring, Printed - Component

**Cond Width** 

#### O-LEADING SUPPLY CHAIN (HK) CO LTD

E490354

ROOM 1205, 12/F TAI SANG BANK BLDG 130-132 DES VOEUS ROAD CENTRAL, HONG KONG

		Min	Cond	SS/	Area	Solo	der	Oper		Meets	c
	Min	Edge	Thk	DS/	Diam	Lim	its	Temp	Flame	UL796	T
Type	mm(in)	mm(in)	mic(mil)	DSO	mm(in)	c	sec	c	Class	DSR	1
Multilayer (m	ass laminate) p	orinted wiring b	ooards.								
O-LEADING- 401	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	12.7 (0.5)	260	10	130	V-0	-	:70
O-LEADING- 407	0.08 (0.003)	0.2 (0.008)	17 (0.67)	DS	9.7 (0.4)	260	10	130	V-0	All	-
Multilayer pri	nted wiring bo	ards.									$\neg$
O-LEADING- 408	0.125 (0.005)	0.125 (0.005)	12 (0.47) Int:136	DS	50.8 (2.0)	280	20	130	V-0	All	*
Single layer p	rinted wiring b	oards.							3 77	700	
O-LEADING- 002	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	105	V-0	All	-
O-LEADING- 003	0.38 (0.015)	1.14 (0.045)	34 (1.34)	SS	19.1 (0.8)	260	10	130	V-0	<b>A</b>	200
O-LEADING- 033	0.15 (0.006)	0.3 (0.012)	34 (1.34)	SS	25.4 (1.0)	260	10	120	V-0	All	
O-LEADING- 205	0.1 (0.004)	0.3 (0.012)	34 (1.34)	DS	69.6 (2.7)	260	10	130	V-0	All	120
O-LEADING- 206	0.15 (0.006)	0.33 (0.013)	17 (0.67)	DS	69.6 (2.7)	260	10	130	V-0	All	==
O-LEADING- D01	0.14 (0.006)	0.15 (0.006)	33 (1.30)	DS	25.4 (1.0)	260	10	130	V-0	All	*
O-LEADING- S01	0.25 (0.010)	0.25 (0.010)	17 (0.67)	SS	25.4 (1.0)	260	4	130	V-0	All	*

#### WIRING, PRINTED - COMPONENT | UL Product iQ

O-LEADING- S02	0.2 (0.008)	0.2 (0.008)	17 (0.67)	SS	25.4 (1.0)	260	4	130	НВ	<b>A</b>	*
O-LEADING- S03	0.25 (0.010)	0.25 (0.010)	34 (1.34)	SS	25.4 (1.0)	260	4	130	V-0	All	*

 $<sup>\</sup>mbox{\ensuremath{\star}}$  - CTI marking is optional and may be marked on the printed wiring board.

Marking: Company name or file number and type designation. May be followed by a suffix to denote factory identification or burning test classification.

并不是所有出现在本数据库中的公司名称和产品都满足了UL 跟踪检验服务的要求。只有带有 UL 标志的产品,才应该被视为经过UL认证,并满足UL 跟踪检验服务的要求。注意查看产品上的标志。

UL 允许在线认证目录中所含材料的复制遵循以下条件: 1.指南信息、装配、构造、设计、系统和/或认证(文件)必须在不篡攻任何数据(或图纸)的情况下完整且无误导性地呈现。2."经 UL 允许从在线认证目录转载"声明必须出现在所摘取材料的邻近位置。此外,转载材料必须包含以下格式的版权声明:"© 2019 UL LLC"

Process Capability					
PCB Production Capabilities					
Layer Count	1Layer-32Layer				
Finished copper thickness	1/3oz-12oz				
Min Line width/spacing internal	3.0mil/3.0mil				
Min Line width/spacing external	4.0mil/4.0mil				
Max Aspect Ratio	10:1				
Board thickness	0.2mm-5.0mm				
Max Panel size(inches)	635*1500mm				
Minimum Drilled Hole Size	4mil				
Plated Hole Tolerance	+/-3mil				
Blind/Buried Vias (All Types)	YES				
Via Fill(Conductive,Non-Conductive)	YES				
Base Material	FR-4,FR-4high Tg.Halogen fi	ree material,Rogers,Aluminium base,Polyimide,Heavy Copper			
Surface finishes	HASL,OSP,ENIG,HAL-LF,lm	mersion silver,lmmersion Tin,Gold fingers,Carbon ink			
SMT Production Cap					
PCB Material		FR-4,CEM-1,CEM-3,Aluminum-based board,FPC			
Max PCB size		510x1500mm			
Min PCB size		50x50mm			
PCB Thickness		0.5mm-4.5mm			
Board thickness		0.5-4mm			
Min Components size		0201			
Standard chip size component		0603 and larger			
Component max height		15mm			
Min lead pitch		0.3mm			
Min BGA ball pitch		0.4mm			
Placement precision		+/-0.03mm			

# Packaging & Delivery

# Shipping service











	Quick Turn Lead Time					
Layer Count:	Lead Tim	Special Requirement				
1L/2L	2-3days	24 Hours,48 Hours				
4L	3-4days	48 Hours				
6L	4-5days	72 Hours				
8L	5-6days	NA				
10L	6-7days	NA				
12L	7-8days	NA				
14L	8-9days	NA				

	Standard Lead Time					
Layer Count:	Sample Lead Time	Volume order lead time				
2L	4 days	10 days				
4L	5 days	11 days				
6L	6 days	12 days				
8L	8 days	14 days				
10L	10 days	16 days				
12L	12 days	18 days				
14L	14 days	20 days				
16-32L	18 days	24 days				

### **FAQ**

#### 1. How do O-Leading ensure quality?

Our high quality standard is achieved with the following.

- 1.1 The process is strictly controlled under ISO 9001:2008 standards.
- 1.2 Extensive use of software in managing the production process
- 1.3 State-of-art testing equipments and tools. E.g. Flying Probe, X-ray Inspection, AOI (Automated Optical Inspector) and ICT (in-circuit testing).
- 1.4. Dedicated quality assurance team with failure case analysis process
- 1.5. Continuous staff training and education

#### 2. How do O-Leading keep your price competitive?

Over the last decade, prices of many raw materials (e.g. copper, chemicals) had doubled, tripled or quadrupled; Chinese currency RMB had appreciated 31% over US dollar; And our labor cost also increased significantly.

However, O-Leading have kept our pricing steady. This owns entirely to our innovations in reducing cost, avoiding wastes and improving efficiency. Our prices are very competitive in the industry at the same quality level.

We believe in a win-win partnership with our customers. Our partnership will be mutually beneficial if we can provide you an edgeon cost and quality.

#### 3. What kinds of boards can O-Leading process?

Common FR4, high-TG and halogen-free boards, Rogers, Arlon, Telfon, aluminum/copper-based boards, PI, etc.

#### 4. What data are needed for PCB & PCBA production?

- 4.1 BOM (Bill of Materials) with reference designators: component description, manufacturer's name and part number.
- 4.2 PCB Gerber files.
- 4.3 PCB fabrication drawing and PCBA assembly drawing.
- 4.4 Test procedures.
- 4.5 Any mechanical restrictions such as assembly height requirements.

#### 5. What's the typical process flow for multi-layer PCB?

Material cutting  $\rightarrow$  Inner dry film  $\rightarrow$  inner etching  $\rightarrow$  Inner AOI  $\rightarrow$  Multi-bond  $\rightarrow$  Layer stack up Pressing  $\rightarrow$  Drilling  $\rightarrow$  PTH  $\rightarrow$  Panel Plating  $\rightarrow$  Outer Dry Film  $\rightarrow$  Pattern Plating  $\rightarrow$  Outer etching  $\rightarrow$  Outer AOI  $\rightarrow$  Solder Mask  $\rightarrow$  Component Mark  $\rightarrow$  Surface finish  $\rightarrow$  Routing  $\rightarrow$  E/T  $\rightarrow$  Visual Inspection.

#### 6. What's the key equipments for HDI manufacturing?

Key equipment list is as following: Laser drilling machine, Pressing machine, VCP line, Automatic Exposing machine, LDI and etc.

The equipments we have are the best in the industry, laser drilling machines are from Mitsubishi and Hitachi, LDI machines are from Screen(Japan), Automatic Exposing machines are also from Hitachi, all of them make we can meet customer's technical requirements.

#### 7. How many types of surface finish O-lead can do?

O-the leader has the full series of surface finish, such as: ENIG, OSP, LF-HASL, gold plating (soft/hard), immersion silver, Tin, silver plating, immersion tin plating, carbon ink and etc. .. OSP, ENIG, OSP + ENIG commonly used on the HDI, we usually recommend that you use a client or OSP OSP + ENIG if BGA PAD size less than 0.3 mm.

#### 8. What's your capability for FPC? Can O-Leading provide SMT service also?

O-Leading can fabricate FPC from single layer to 8layer, the working panel size can be as large as 2000mm\*240mm, please find the details in the page "Flex Capability" We also provide SMT one stop service to customer.

#### 9. What are the main factors which will affect the price of PCB?

Material;

Surface finish;

Technology difficulty;

Different quality criteria;

PCB characteristics;

Payment terms;

Different manufacturing countries.

#### 10. What's the definition of PCB, PWB and FPC and what's the difference?

PCB is short for Printed Circuit Board;

PWB is short for Printed Wire Board, same meaning as Printed Circuit Board;

FPC is short for Flexible Printed Board.

#### 11. What factors should be considered when choosing the material for a PCB board?

Below factors should be considered when we choose the material for PCB:

The material's Tg value should be greater than the operation temperature;

Low CTE material has good performance of thermal stability;

Good thermal resistance performance: Normally PCBs are required to resist 250°C for at least 50s. Good flatness; In consideration of the electrical properties, low loss/high permittivity material is used on high frequency PCB; Polyimide glass fiber substrate used for flexible PCB; Metal core is used when the product has strict requirement of heat dissipation.

#### 12. What's the merits of O-leading's rIgid-flex PCB?

O-leading's rigid-flex PCB has the characters of both FPC and PCB, so it can be used in some special products. Some part is flexible while the other part rigid, it can help save product's interior space, reduce product volume and improve performance.

#### 13. How to you make the impedance calculation?

The impedance control system is done using some test coupons, the SI6000 soft and the CITS 500s equipment from POLAR INSTRUMENTS.

The equipment measures the impedance on a representative track configuration coupon of which the client has given us a determinate value and tolerance.